

SMA/DO-214AC

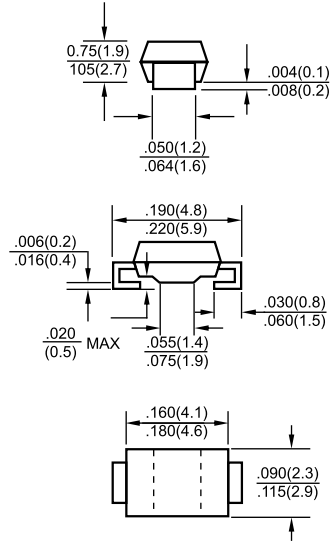


Features

- ✧ For surface mounted application
- ✧ Glass passivated junction chip
- ✧ Built-in strain relief, ideal for automated placement
- ✧ Plastic material used carries Underwriters Laboratory Classification 94V-0
- ✧ Fast switching for high efficiency
- ✧ High temperature soldering: 260°C/ 10 seconds at terminals

Mechanical Data

- ✧ Cases: Molded plastic
- ✧ Terminals: Pure tin plated, Lead free.
- ✧ Polarity: Indicated by cathode band
- ✧ Packing: 12mm tape
- ✧ Weight: 0.064 gram



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

| Type Number | Symbol | RS1A | RS1B | RS1D | RS1G | RS1J | RS1K | RS1M | Units |
|---|------------------------------------|-------------|------|------|------|------|------|------|-----------------------------|
| Maximum Recurrent Peak Reverse Voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS Voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum Average Forward Rectified Current See Fig. 1 @ $T_L=90^\circ\text{C}$ | $I_{(AV)}$ | 1.0 | | | | | | | A |
| Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) | I_{FSM} | 30 | | | | | | | A |
| Maximum Instantaneous Forward Voltage @ 1.0A | V_F | 1.3 | | | | | | | V |
| Maximum DC Reverse Current @ $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$ | I_R | 5 50 | | | | | | | uA uA |
| Maximum Reverse Recovery Time (Note 1) | T_{rr} | 150 | | | | 250 | 500 | | nS |
| Typical Junction Capacitance (Note 2) | C_j | 10 | | | | | | | pF |
| Typical Thermal Resistance (Note 3) | $R_{\theta JA}$ $R_{\theta JL}$ | 105 32 | | | | | | | $^\circ\text{C} / \text{W}$ |
| Operating Temperature Range | T_J | -55 to +150 | | | | | | | $^\circ\text{C}$ |
| Storage Temperature Range | T_{STG} | -55 to +150 | | | | | | | $^\circ\text{C}$ |

- Notes:
1. Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$
 2. Measured at 1 MHz and Applied $V_R=4.0$ Volts
 3. Thermal Resistance from Junction to Ambient and from Junction to Lead Mounted on P.C.B. with 0.2"x0.2" (5.0 x 5.0 mm) Copper Pad Areas.

RATINGS AND CHARACTERISTIC CURVES (RS1A THRU RS1M)

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

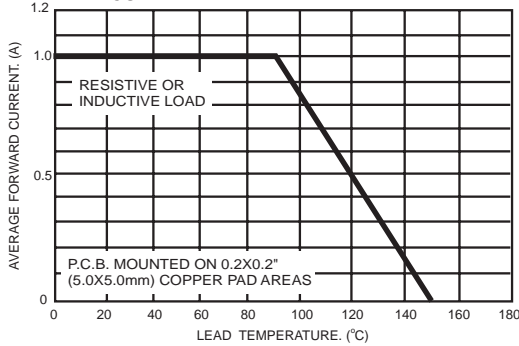


FIG.2- TYPICAL REVERSE CHARACTERISTICS

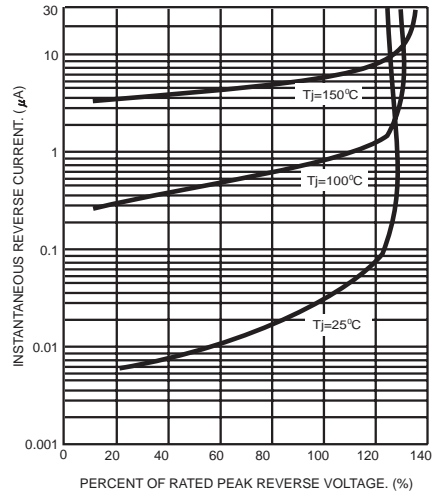


FIG.3- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

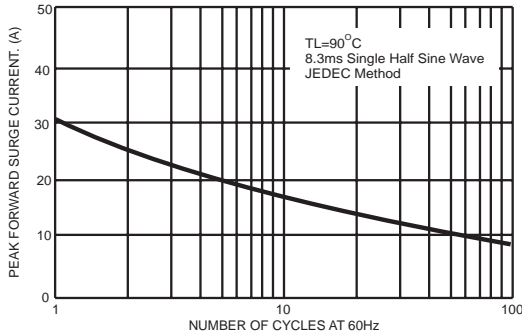


FIG.5- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS PER LEG

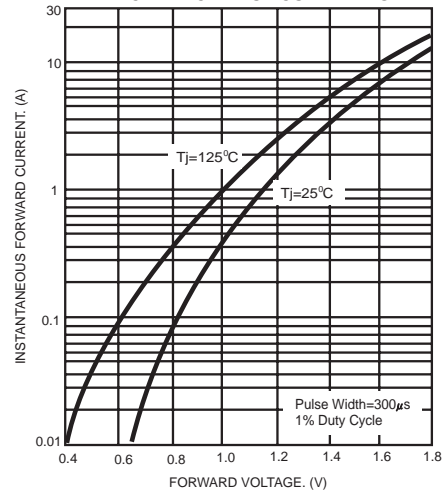


FIG.4- TYPICAL JUNCTION CAPACITANCE

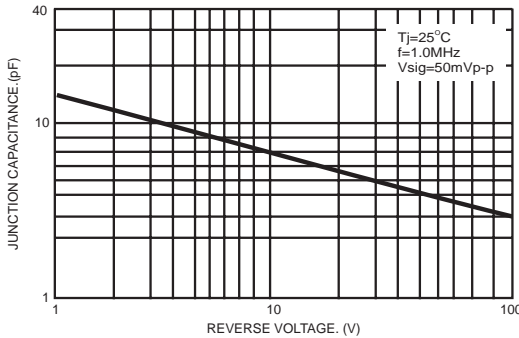


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

